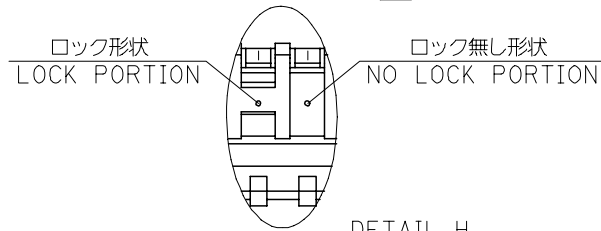
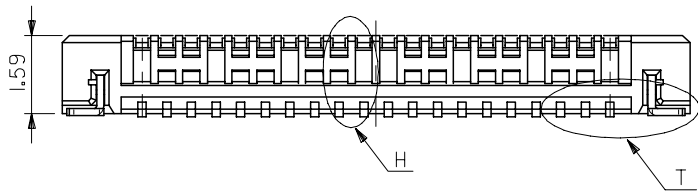
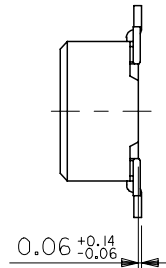
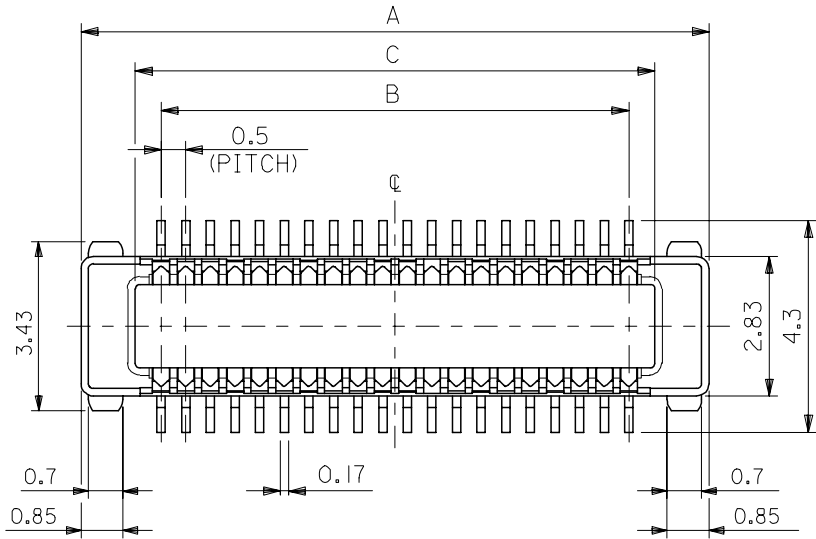


注記
NOTES:

- 材質
MATERIAL
ハウジング: LCP (液晶ポリマー)、ガラス充填、黒色、UL94V-0
HOUSING: LCP (LIQUID CRYSTAL POLYMER), GLASS FILLED, BLACK, UL94V-0
ターミナル: 銅合金 (t=0.15)
TERMINAL: COPPER ALLOY (t=0.15)
ネイル: 銅合金 (t=0.15)
NAIL: COPPER ALLOY (t=0.15)
- メッキ仕様
PLATING
ターミナル
TERMINAL
接点部: 金メッキ 0.25マイクロメートル以上
CONTACT AREA: GOLD 0.25 MICROMETER MINIMUM
半田付け部: 金メッキ 0.35マイクロメートル以下
SOLDER TAIL AREA: GOLD 0.35 MICROMETER MAXIMUM
下地メッキ: ニッケルメッキ 1.5マイクロメートル以上
UNDER PLATING: NICKEL 1.5 MICROMETER MINIMUM
ネイル
NAIL
錫メッキ 1.0マイクロメートル以上
TIN 1.0 MICROMETER MINIMUM
下地メッキ: ニッケルメッキ 1.0マイクロメートル以上
UNDER PLATING: NICKEL 1.0 MICROMETER MINIMUM
- テール平坦度は、0.08ミリメートル以下。テールとネイルを併せた平坦度は、0.1ミリメートル以下。
TAIL COPLANARITY TO BE 0.08 MAXIMUM. TAILS AND NAILS COPLANARITY TO BE 0.1 MAXIMUM.
- 嵌合相手: 54363-****
MATED CONN.: 54363-****
- 本製品は55650-****1の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 55650-****1

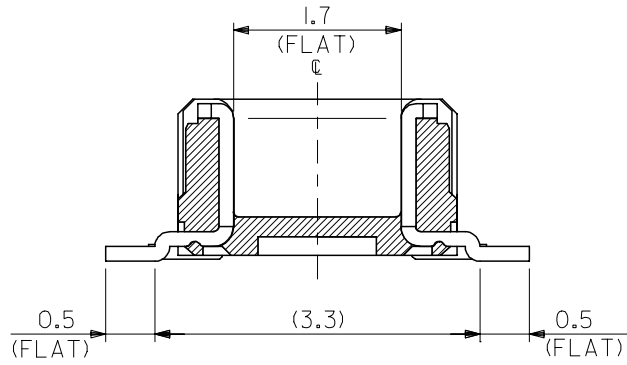


DETAIL H
SCALE 2:1

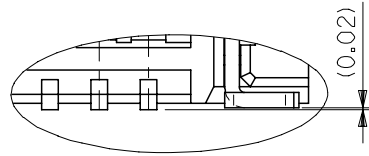
—#	28.05	27	30.25	55650-1181	110
4	18.05	17	20.25	55650-0781	70
8	15.55	14.5	17.75	55650-0681	60
12	13.05	12	15.25	55650-0581	50
20	10.55	9.5	12.75	55650-0481	40
30	8.05	7	10.25	55650-0381	30
20	5.55	4.5	7.75	55650-0281	20
ロック数 LOCKS	C	B	A	製品番号 MATERIAL NO.	極数 CIRCUITS

MODEL NO. 55650-***1

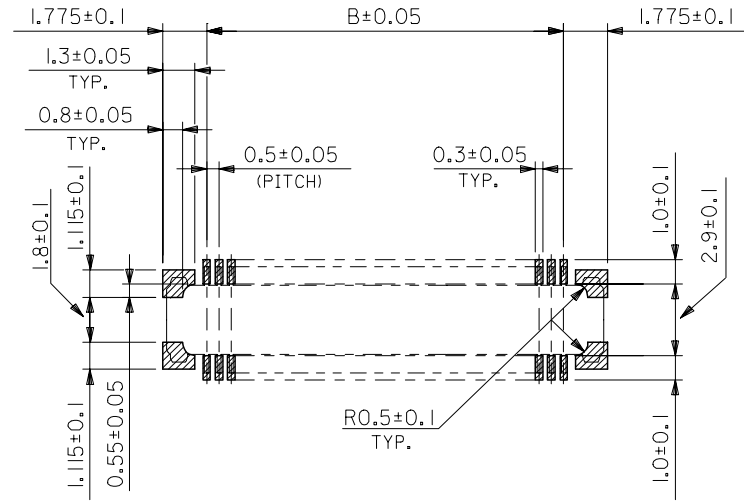
REVISED EC NO: J2008-0540 DRWN: A0YAGI 2007/09/03 CHKD: TOYODA 2007/09/03 APPR: NUKITA 2007/09/04	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY M. NAGATA	DATE 2004/03/09	TITLE 0.5 MM PITCH B/B CONN. PLUG NAIL ASS'Y (H=2MM) -LEAD FREE-		
	10 OVER 30 UNDER	±0.25	CHECKED BY K. TOJO	DATE 2004/03/09	MOLEX MOLEX INCORPORATED		
	30 OVER	±0.3	APPROVED BY M. SASAO	DATE 2004/03/09	MATERIAL NO. SEE TABLE	DOCUMENT NO. SD-55650-013	SHEET NO. 1 OF 2
	ANGULAR	±3 °	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION	



製品断面図 (半田付け部、吸着面寸法)
 DETAIL FOR SOLDERING AND VACUUM AREA

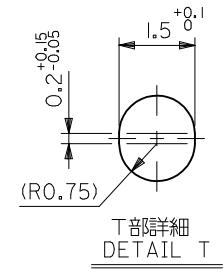
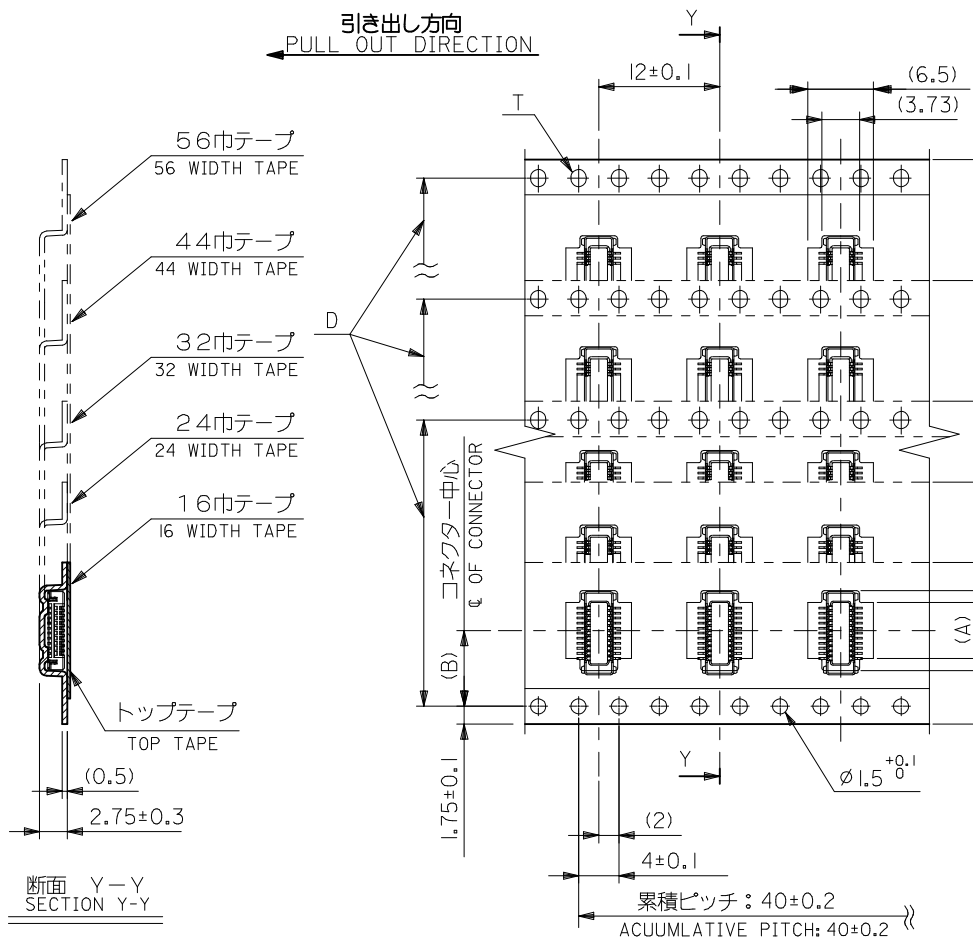


DETAIL T
 T部詳細



推奨基板寸法
 RECOMMENDED PCB PATTERN LAYOUT
 (SCALE 5:1)

REVISED EC NO: J2008-0540 DRWN: A0YAGI 2007/09/03 CHKDK: TOYODA 2007/09/03 APPR: NUKITA 2007/09/04	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	10 UNDER	± 0.2	DRAWN BY M. NAGATA	DATE 2004/03/09	TITLE 0.5 MM PITCH B/B CONN. PLUG NAIL ASS'Y (H=2MM) -LEAD FREE-			
	10 ^{OVER} 30 UNDER	± 0.25	CHECKED BY K. TOJO	DATE 2004/03/09	MOLEX INCORPORATED			
	30 ^{OVER}	± 0.3	APPROVED BY M. SASAO	DATE 2004/03/09	MATERIAL NO. SEE SHEET 1			
	ANGULAR	± 3 °	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		DOCUMENT NO. SD-55650-013	SHEET NO. 2 OF 2		



37.5	33.4	32±0.3	28.4	20.45 17.95	14.2	18.05 15.55	55650-0788	70
29.4	25.4	24±0.3	#	15.45 12.95	11.5	13.05 10.55	55650-0688	60
21.4	17.4	16±0.3	#	10.45	7.5	8.05	55650-0588	50
G	F	E	D	(C)	(B)	(A)	55650-0488	40
				7.95	5.55	5.55	55650-0388	30
							55650-0288	20
E キャリアテープ幅 CARRIER TAPE WIDTH							製品番号 MATERIAL NO.	極数 CIRCUITS

MATERIAL 材料	注記参照 SEE NOTES	REVISED	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE MM ONLY	SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
FINISH 仕上げ	注記参照 SEE NOTES	EC NO: J2009-0552	DRWN: YOSHIDAM 2008/12/04	10 UNDER ±0.2	DRAWN BY M. NAGATA	DATE 2004/03/09	TITLE EMBOSSD TAPE PACKAGE FOR 55650-***81 -LEAD FREE-	
WIRE RANGE 適用電線範囲	#	CHKD: THARUYAMA 2008/12/04	APPR: NUKITA 2008/12/08	10 OVER 30 UNDER ±0.25	CHECKED BY K. TOJO	DATE 2004/03/09	MOLEX INCORPORATED	
INS. RANGE 被覆外径	#			30 OVER ±0.3	APPROVED BY M. SASAO	DATE 2004/03/09	DOCUMENT NO. SD-55650-014	SHEET NO. 2 OF 2
				ANGULAR ±3 °	MATERIAL NO. SEE TABLE	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		
				DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	SIZE A3			